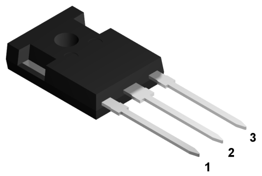
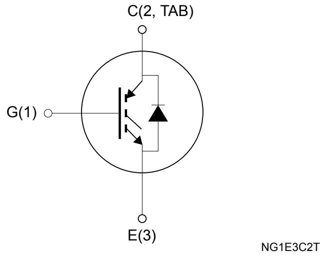
STGWA40H65DFB2

Datasheet

Trench gate field-stop, 650 V, 40 A, high-speed HB2 series IGBT in a TO-247 long leads package



TO-247 long leads



Features

- Maximum junction temperature: T_J = 175 °C
- Low $V_{CE(sat)}$ = 1.55 V(typ.) @ I_C = 40 A
- Very fast and soft recovery co-packaged diode
- Minimized tail current
- Tight parameter distribution
- Low thermal resistance
- Positive $V_{CE(sat)}$ temperature coefficient

Applications

- Welding
- Power factor correction
- UPS
- Solar inverters
- Chargers

Description

The newest IGBT 650 V HB2 series represents an evolution of the advanced proprietary trench gate field-stop structure. The performance of the HB2 series is optimized in terms of conduction, thanks to a better $V_{CE(sat)}$ behavior at low current values, as well as in terms of reduced switching energy. A very fast soft recovery diode is co-packaged in antiparallel with the IGBT. The result is a product specifically designed to maximize efficiency for a wide range of fast applications.

Product status link
STGWA40H65DFB2

Product summary	
Order code	STGWA40H65DFB2
Marking	G40H65DFB2
Package	TO-247 long leads
Packing	Tube

1 Electrical ratings

Table 1. **Absolute maximum ratings**

Symbol	Parameter	Value	Unit
V_{CES}	Collector-emitter voltage (V_{GE} = 0 V)	650	V
I_C	Continuous collector current at T_C = 25 °C	72	A
	Continuous collector current at T_C = 100 °C	45	
I_{CP} (1)	Pulsed collector current ($t_p \leq 1$ µs, T_J < 175 °C)	160	
V_{GE}	Gate-emitter voltage	±20	V
	Transient gate-emitter voltage ($t_p \leq 10$ µs)	±30	
I_F	Continuous forward current at T_C = 25 °C	60	A
	Continuous forward current at T_C = 100 °C	38	
I_{FP}(1)	Pulsed forward current ($t_p \leq 1$ µs, T_J < 175 °C)	160	
P_{TOT}	Total power dissipation at T_C = 25 °C	230	W
T_{STG}	Storage temperature range	-55 to 150	°C
T_J	Operating junction temperature range	-55 to 175	

1. *Defined by design, not subject to production test.*

Table 2. **Thermal data**

Symbol	Parameter	Value	Unit
R_{thJC}	Thermal resistance junction-case IGBT	0.65	°C/W
	Thermal resistance junction-case diode	1.14	
R_{thJA}	Thermal resistance junction-ambient	50	

2 Electrical characteristics

T_C = 25 °C unless otherwise specified

Table 3. **Static characteristics**

Symbol	Parameter	Test conditions	Min.	Typ.	Max.	Unit
$V_{(BR)CES}$	Collector-emitter breakdown voltage	V_{GE} = 0 V, I_C = 1 mA	650			V
$V_{CE(sat)}$	Collector-emitter saturation voltage	V_{GE} = 15 V, I_C = 40 A		1.55	2	V
		V_{GE} = 15 V, I_C = 40 A, T_J = 125 °C		1.75		
		V_{GE} = 15 V, I_C = 40 A, T_J = 175 °C		1.85		
V_F	Forward on-voltage	I_F = 40 A		1.7	2.45	V
		I_F = 40 A, T_J = 125 °C		1.4		
		I_F = 40 A, T_J = 175 °C		1.3		
$V_{GE(th)}$	Gate threshold voltage	V_{CE} = V_{GE}, I_C = 1 mA	5	6	7	V
I_{CES}	Collector cut-off current	V_{GE} = 0 V, V_{CE} = 650 V			25	µA
I_{GES}	Gate-emitter leakage current	V_{CE} = 0 V, V_{GE} = ±20 V			±250	nA

Table 4. **Dynamic characteristics**

Symbol	Parameter	Test conditions	Min.	Typ.	Max.	Unit
C_{ies}	Input capacitance	V_{CE} = 25 V, f = 1 MHz, V_{GE} = 0 V	-	2300	-	pF
C_{oes}	Output capacitance		-	122	-	
C_{res}	Reverse transfer capacitance		-	64	-	
Q_g	Total gate charge	V_{CC} = 520 V, I_C = 40 A, V_{GE} = 0 to 15 V (see Figure 28. Gate charge test circuit)	-	153	-	nC
Q_{ge}	Gate-emitter charge		-	29	-	
Q_{gc}	Gate-collector charge		-	67	-	

Table 5. Switching characteristics (inductive load)

Symbol	Parameter	Test conditions	Min.	Typ.	Max.	Unit
$t_{d(on)}$	Turn-on delay time	V_{CC} = 400 V, I_C = 40 A, V_{GE} = 15 V, R_G = 4.7 Ω (see Figure 27. Test circuit for inductive load switching)	-	18	-	ns
t_r	Current rise time		-	10.2	-	ns
E_{on}(1)	Turn-on switching energy		-	765	-	µJ
$t_{d(off)}$	Turn-off delay time		-	72	-	ns
t_f	Current fall time		-	40	-	ns
E_{off} (2)	Turn-off switching energy		-	410	-	µJ
$t_{d(on)}$	Turn-on delay time	V_{CC} = 400 V, I_C = 40 A, V_{GE} = 15 V, R_G = 4.7 Ω, T_J = 175 °C (see Figure 27. Test circuit for inductive load switching)	-	22	-	ns
t_r	Current rise time		-	12	-	ns
E_{on}(1)	Turn-on switching energy		-	1460	-	µJ
$t_{d(off)}$	Turn-off delay time		-	78	-	ns
t_f	Current fall time		-	80	-	ns
E_{off} (2)	Turn-off switching energy		-	780	-	µJ

1. *Including the reverse recovery of the diode.*
2. *Including the tail of the collector current.*

Table 6. Diode switching characteristics (inductive load)

Symbol	Parameter	Test conditions	Min.	Typ.	Max.	Unit
t_{rr}	Reverse recovery time	I_F = 40 A, V_R = 400 V, V_{GE} = 15 V, di/dt = 1000 A/µs (see Figure 30. Diode reverse recovery waveform)	-	75	-	ns
Q_{rr}	Reverse recovery charge		-	730	-	nC
I_{rrm}	Reverse recovery current		-	15	-	A
dI_{rr}/dt	Peak rate of fall of reverse recovery current during t_b		-	725	-	A/µs
E_{rr}	Reverse recovery energy		-	139	-	µJ
t_{rr}	Reverse recovery time	I_F = 40 A, V_R = 400 V, V_{GE} = 15 V, di/dt = 1000 A/µs, T_J = 175 °C (see Figure 30. Diode reverse recovery waveform)	-	125	-	ns
Q_{rr}	Reverse recovery charge		-	3110	-	nC
I_{rrm}	Reverse recovery current		-	37	-	A
dI_{rr}/dt	Peak rate of fall of reverse recovery current during t_b		-	845	-	A/µs
E_{rr}	Reverse recovery energy		-	624	-	µJ

2.1 Electrical characteristics (curves)

Figure 1. Power dissipation vs case temperature

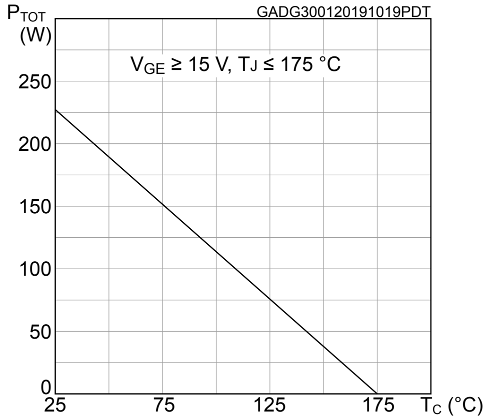


Figure 2. Collector current vs case temperature

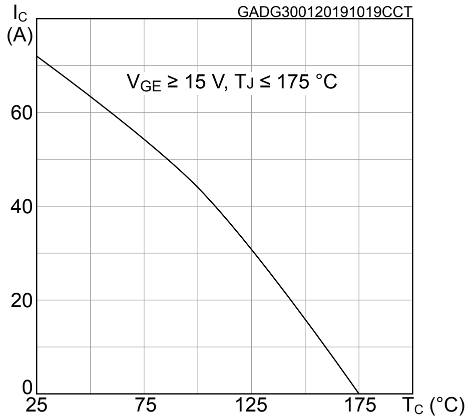


Figure 3. Output characteristics (T_J = 25 °C)

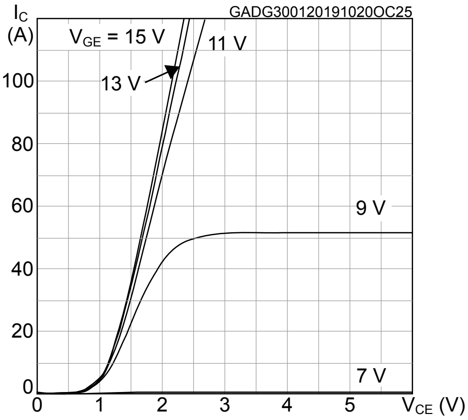


Figure 4. Output characteristics (T_J = 175 °C)

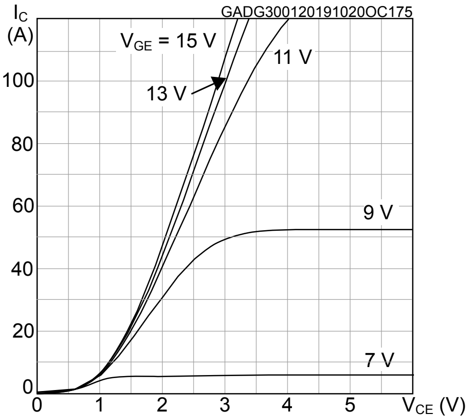


Figure 5. $V_{CE(sat)}$ vs junction temperature

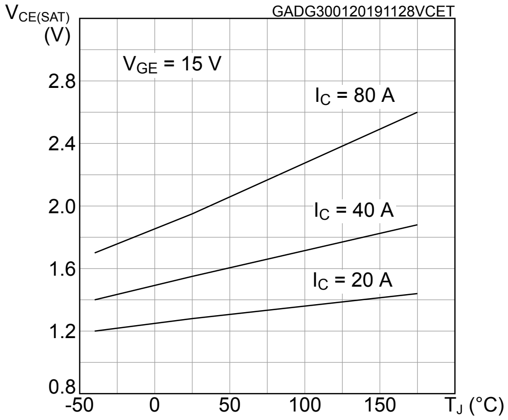


Figure 6. $V_{CE(sat)}$ vs collector current

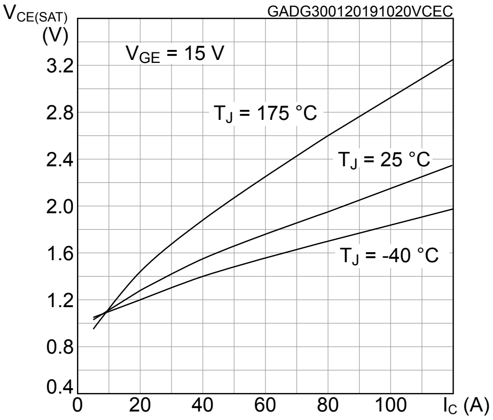


Figure 7. Collector current vs switching frequency

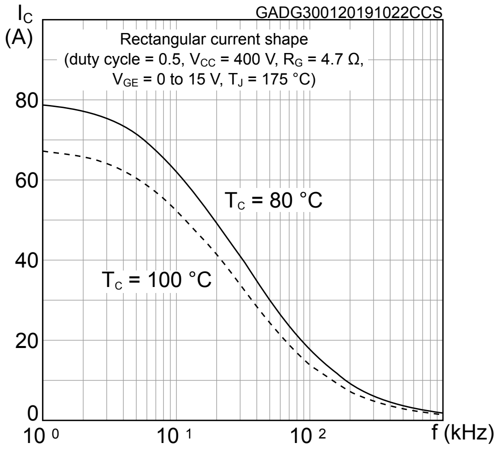


Figure 8. Forward bias safe operating area

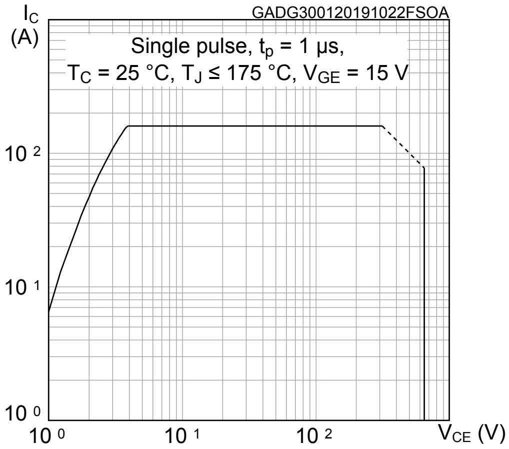


Figure 9. Transfer characteristics

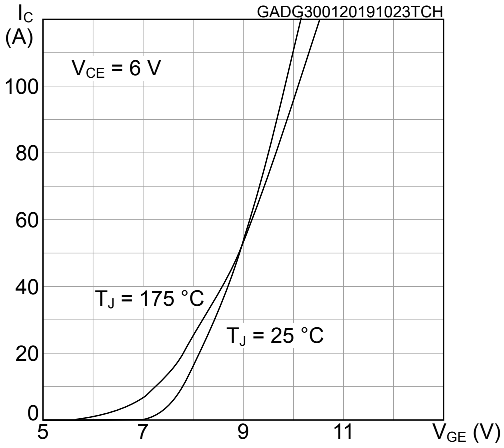


Figure 10. Diode V_F vs forward current

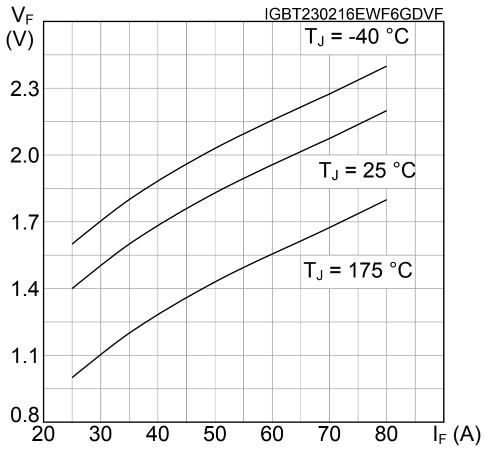


Figure 11. Normalized $V_{GE(th)}$ vs junction temperature

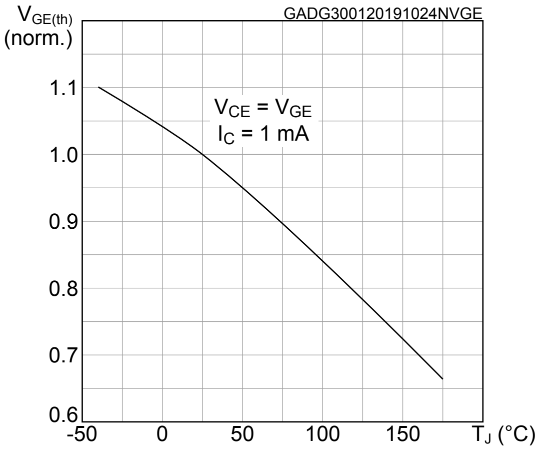


Figure 12. Normalized $V_{(BR)CES}$ vs junction temperature

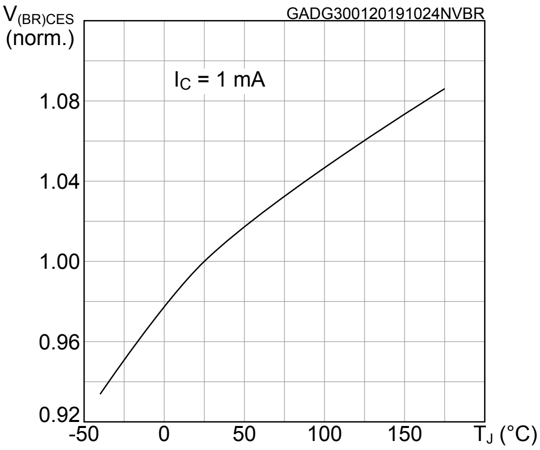


Figure 13. **Capacitance variations**

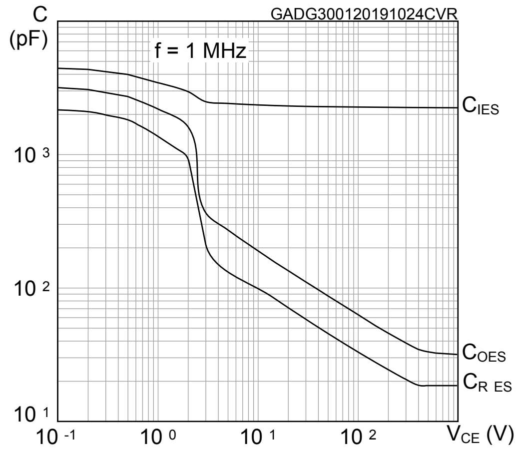


Figure 14. **Gate charge vs gate-emitter voltage**

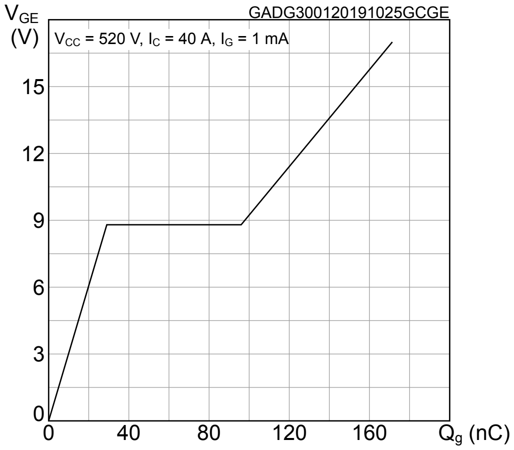


Figure 15. **Switching energy vs collector current**

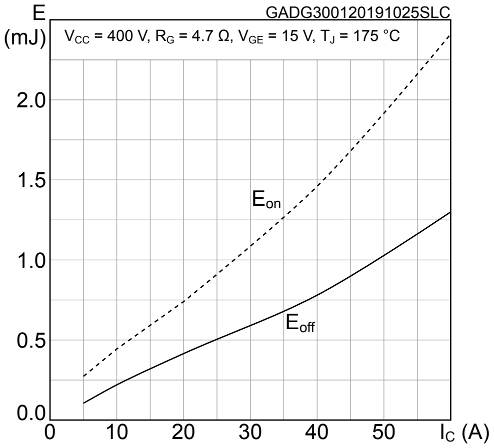


Figure 16. **Switching energy vs temperature**

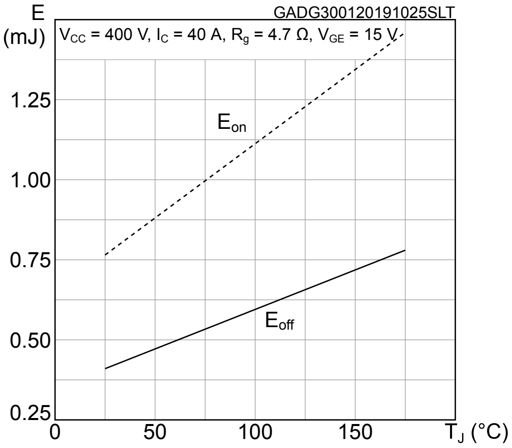


Figure 17. **Switching energy vs collector emitter voltage**

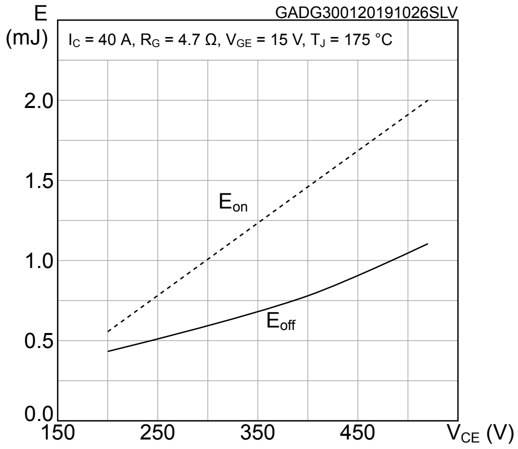
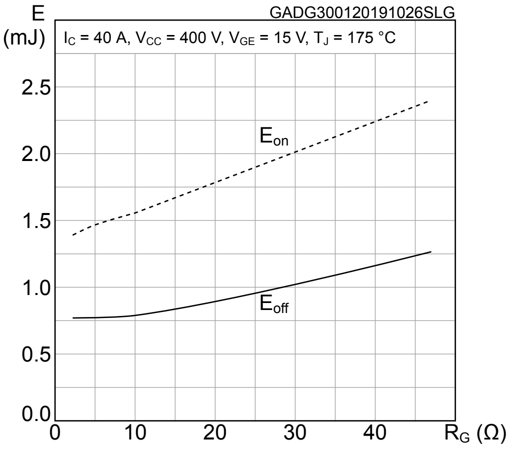


Figure 18. **Switching energy vs gate resistance**



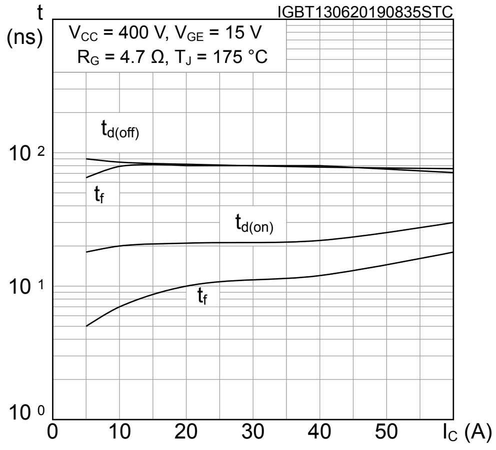


Figure 19. Switching times vs collector current

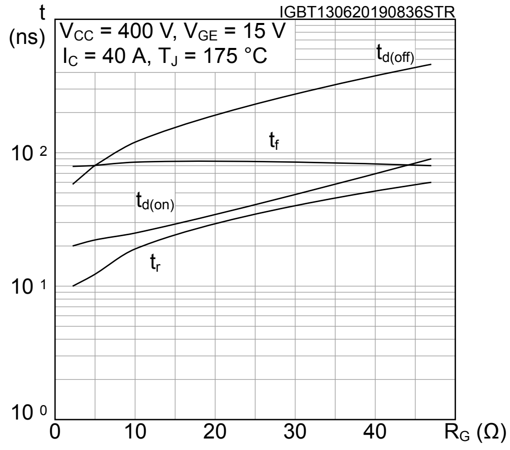


Figure 20. Switching times vs gate resistance

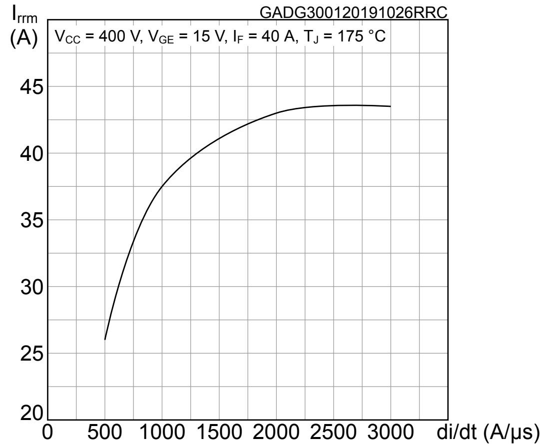


Figure 21. Reverse recovery current vs diode current slope

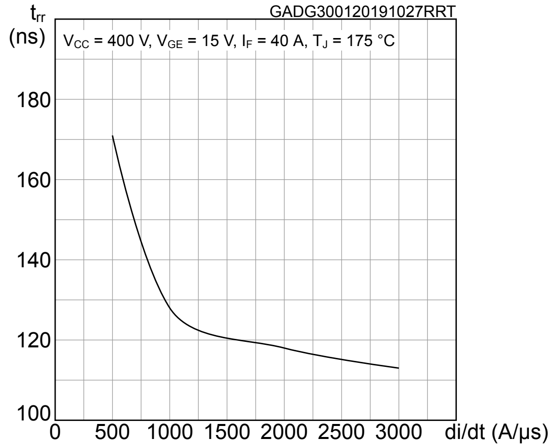


Figure 22. Reverse recovery time vs diode current slope

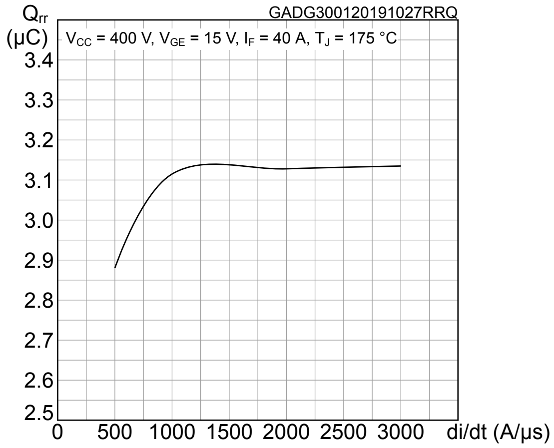


Figure 23. Reverse recovery charge vs diode current slope

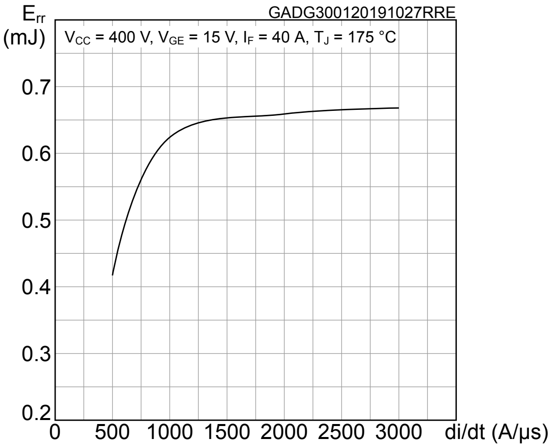


Figure 24. Reverse recovery energy vs diode current slope

Figure 25. Thermal impedance for IGBT

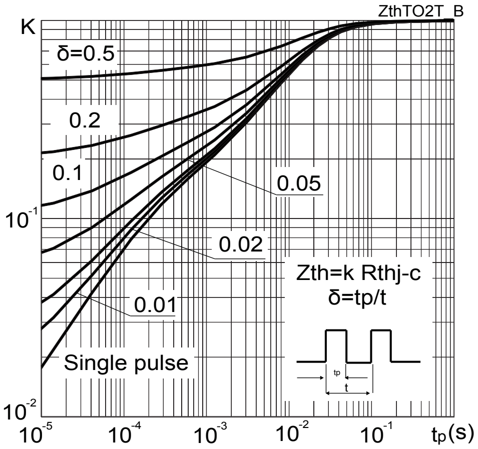
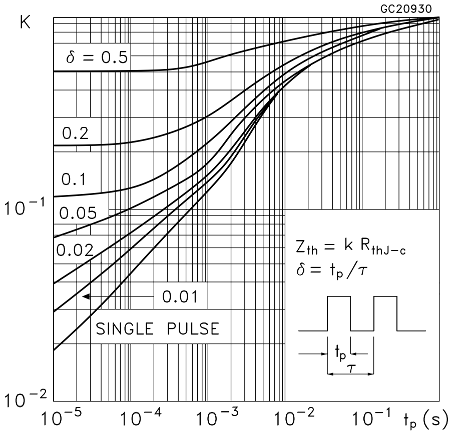
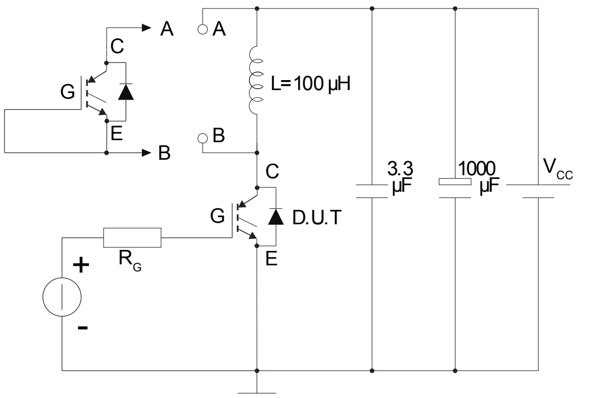


Figure 26. Thermal impedance for diode



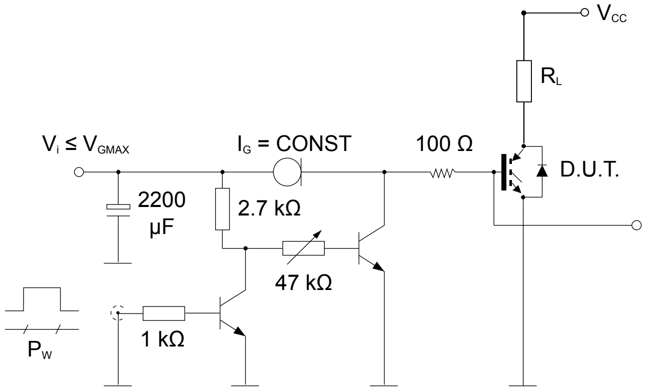
3 Test circuits

Figure 27. **Test circuit for inductive load switching**



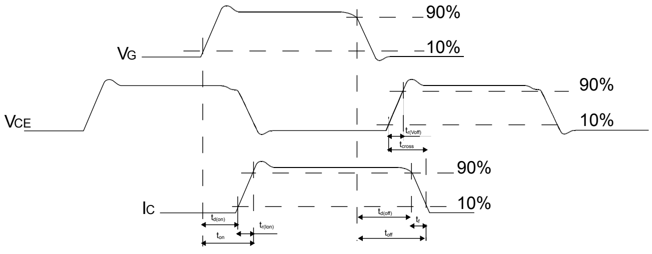
AM01504v1

Figure 28. **Gate charge test circuit**



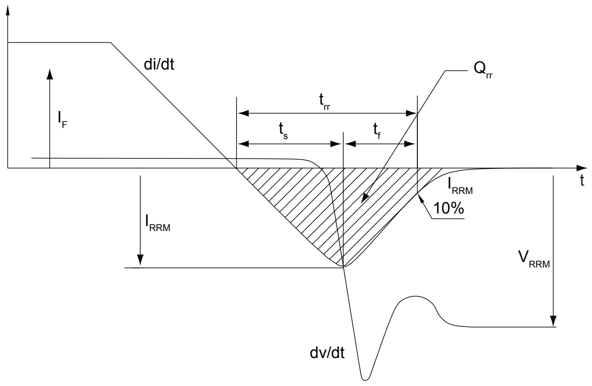
GADG160420181048IG

Figure 29. **Switching waveform**



AM01506v1

Figure 30. **Diode reverse recovery waveform**



GADG180720171418SA

4 Package information

In order to meet environmental requirements, ST offers these devices in different grades of ECOPACK packages, depending on their level of environmental compliance. ECOPACK specifications, grade definitions and product status are available at: www.st.com. ECOPACK is an ST trademark.

4.1 TO-247 long leads package information

Figure 31. **TO-247 long leads package outline**

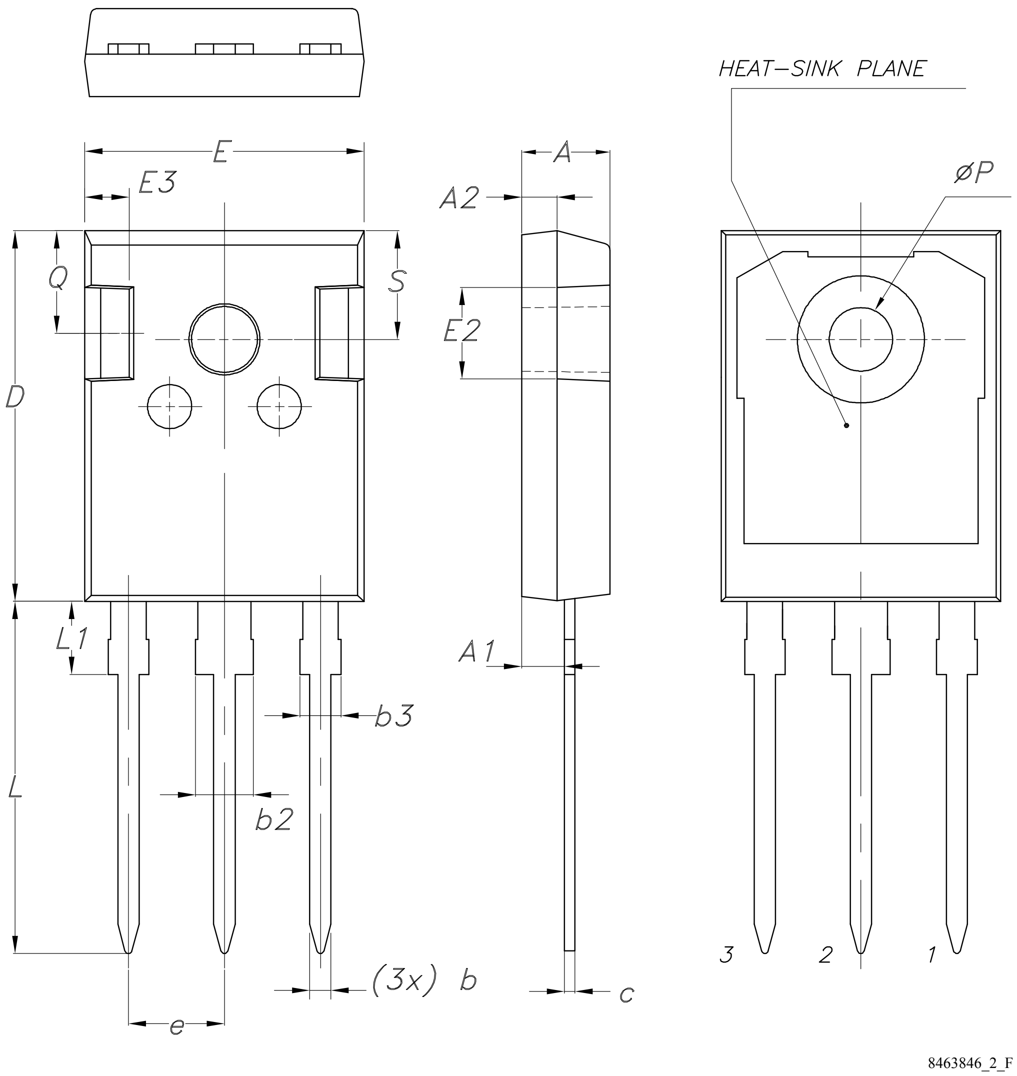


Table 7. TO-247 long leads package mechanical data

Dim.	mm		
	Min.	Typ.	Max.
A	4.90	5.00	5.10
A1	2.31	2.41	2.51
A2	1.90	2.00	2.10
b	1.16		1.26
b2			3.25
b3			2.25
c	0.59		0.66
D	20.90	21.00	21.10
E	15.70	15.80	15.90
E2	4.90	5.00	5.10
E3	2.40	2.50	2.60
e	5.34	5.44	5.54
L	19.80	19.92	20.10
L1			4.30
P	3.50	3.60	3.70
Q	5.60		6.00
S	6.05	6.15	6.25

Revision history

Table 8. Document revision history

Date	Version	Changes
15-Mar-2019	1	First release.
12-Jun-2019	2	Modified Table 1. Absolute maximum ratings, Table 2. Thermal data, Table 5. Switching characteristics (inductive load). Modified Figure 15. Switching energy vs collector current, Figure 16. Switching energy vs temperature, Figure 17. Switching energy vs collector emitter voltage, Figure 18. Switching energy vs gate resistance, Figure 19. Switching times vs collector current and Figure 20. Switching times vs gate resistance. Minor text changes.

Contents

IMPORTANT NOTICE – PLEASE READ CAREFULLY

STMicroelectronics NV and its subsidiaries (“ST”) reserve the right to make changes, corrections, enhancements, modifications, and improvements to ST products and/or to this document at any time without notice. Purchasers should obtain the latest relevant information on ST products before placing orders. ST products are sold pursuant to ST’s terms and conditions of sale in place at the time of order acknowledgement.

Purchasers are solely responsible for the choice, selection, and use of ST products and ST assumes no liability for application assistance or the design of Purchasers’ products.

No license, express or implied, to any intellectual property right is granted by ST herein.

Resale of ST products with provisions different from the information set forth herein shall void any warranty granted by ST for such product.

ST and the ST logo are trademarks of ST. For additional information about ST trademarks, please refer to www.st.com/trademarks. All other product or service names are the property of their respective owners.

Information in this document supersedes and replaces information previously supplied in any prior versions of this document.

© 2019 STMicroelectronics – All rights reserved